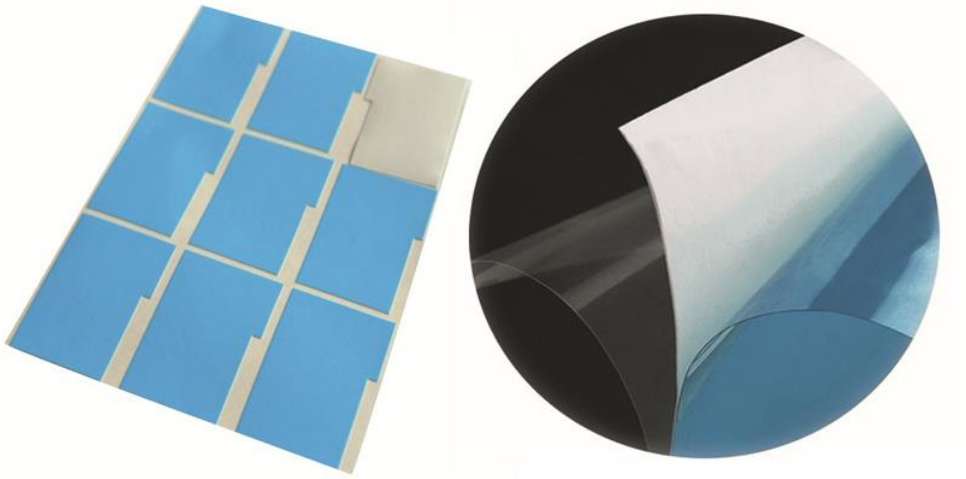

All of our Thermal Conductive Adhesive Tape is used for bonding heat disspation fins to microprocessor or power consumption semiconductors, utlimate bonding strength with lower thermal resistance without mechanical fixing for assembly

-Double-sided, pressure sensitive adhesive tape

-Electrically insulating

Typical Application:

- Mount heat sink/spreader onto drive process(BGA)/power converter or Motor control PCB

- In all applications where a metal/plastic housing is used as heatsink without screw or clip mounting and hot-melt glue

Typical Properties of Thermal Conductive Adhesive Tape								
Properties	**Units**	**TCT120**		**TCT120FG**				**Test Method**
Color	---	White		White				Visual
Reinforcement Carrier	---	No		Fiberglass				---
Thickness Range	mm	0.15	0.25	0.15	0.2	0.25	0.3	---
natural tacky (1- or 2-sided)	---	2	2	2	2	2	2	---
Continuous Use Temp	℃	-20 to 100						EN344
ELECTRICAL								
Breakdown Voltage	Kv/mm	≥2	≥4	≥2	≥2.5	≥3.5	≥4	ASTM D149
Peel Adhesion	N/25mm	9.5	11	10.3	11.8	14.5	15.8	PSTC-7
Holding Adhesion	N/25mm/25℃	10.2	11.8	12.2	14.5	16.8	18	PSTC-7
THERMAL								
Thermal Conductivity	W/m.k	1.2	1.2	1.2	1.2	1.2	1.2	ASTM D5470